

MPI TS3500-HP | 300 mm Automated Probe System

For accurate and reliable High Power measurements

FEATURES / BENEFITS

Dedicated designed for High Voltage and High Current application

- On wafer high power device measurement up to 10 kV/600 A
- Gold plated chuck surface for minimum contact resistance and vacuum holes optimized for thin wafer handling down to 50 µm
- Taiko wafer chuck option
- Dedicated high voltage and high current probes
- Anti-arcing solutions

WaferWallet® Option

- Designed with five individual trays for manual, ergonomic loading of 150, 200, or 300 mm “modeling” wafers
- Fully-automated tests with up to five identical wafers at multiple temperatures
- Unique capability to load/unload wafers at any temperature

MPI ShieldEnvironment™ for Accurate Measurements

- Designed for Advanced EMI / RFI / Light-Tight Shielding
- fA low-leakage capabilities
- Ready for temperature range -60 °C to 300 °C

Ergonomic Design and Options

- Easy wafer or single DUT loading from the front
- Integrated active vibration isolation
- Completely integrated prober control for faster, safer and convenient system and test operation
- The Safety Test Management (STM™) with automated dew point control
- Reduced footprint due to smart integration of the chiller
- Instrument shelf option for shorter RF cables providing the highest measurement dynamic



WAFERWALLET® SPECIFICATIONS



Wafer loading trays	5
Supported wafer sizes	150, 200, or 300 mm
Individual notch marks	0, 90, 180 & 270 deg for all wafer sizes
Hot and cold wafer swapping	Yes, local environmental chamber
Wafer pre-aligner	For 150, 200 and 300 mm, option
Wafer ID-Reader	Option for top or bottom ID reading Revolutionary integrated RGB illumination Fully automatic exposure control Code shift compensation OCR, Barcode, DataMatrix and QR code
Signal light tower	Four color, LED steady/flashing tower lights

STAGE SPECIFICATIONS

Chuck XY Stage (Programmable)

Travel range	305 mm x 520 mm (12.0 x 20.5 in)
Resolution	0.5 μ m
Accuracy	< 2.0 μ m (0.08 mils)
Repeatability	< 1.0 μ m
XY stage drive	Closed-loop high precision stepper motors
Speed*	Slowest: 10 μ m / sec Fastest: 50 mm / sec

Chuck Z Stage (Programmable)

Travel range	30 mm (1.18 in)
Resolution	0.2 μ m
Accuracy	< 2.0 μ m
Repeatability	< 1.0 μ m
Z stage drive	Closed-loop high precision stepper motor
Speed*	Slowest: 10 μ m / sec Fastest: 20 mm / sec
Guider	Precision ball bearings

*The speed is instantaneous speed, not average speed. There is accelerate and decelerate time when moving.

STAGE SPECIFICATIONS

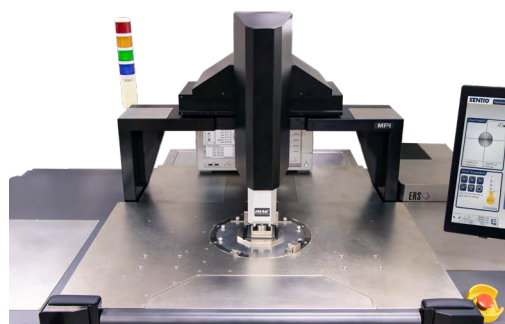
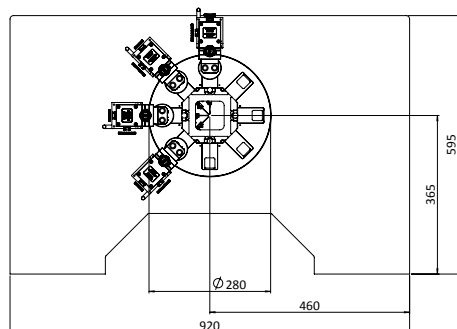
Chuck Theta Stage (Programmable)

Travel range	$\pm 5.0^\circ$
Resolution	0.0001° (0.24 μ m @ 300mm edge)
Accuracy	< 2.0 μ m (measured at the edge of the 300 mm chuck)
Repeatability	< 1.0 μ m
Theta stage drive	High resolution stepper motor with linear encoder feedback system

PROBE PLATEN

Specifications

Material	Nickel plated steel
Chuck to platen height	50 \pm 0.5 mm
Platen cooling	Fully integrated CDA cooling, by using the chiller CDA
Configuration	Probe card holder 4.5 x 7" and/or MicroPositioners
Max. No. of MicroPositioners	8x DC MicroPositioners or 4x DC + 4x RF MicroPositioner Setup
RF MicroPositioner mounting	Magnetic with guided rail
DC MicroPositioner mounting	Magnetic



Large Probe Platen supporting up to 8x DC or 4x DC + 4x RF MicroPositioners or standard 4.5" probe card holder

ShieldEnvironment™

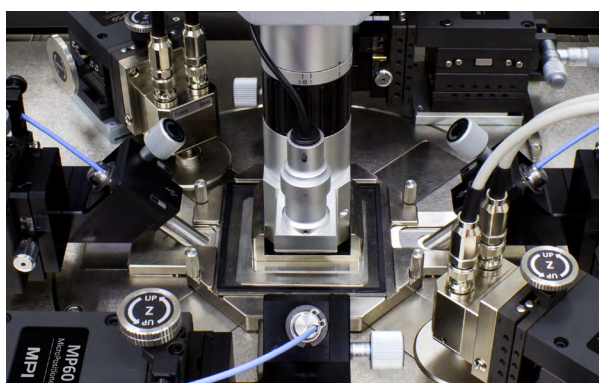
MPI ShieldEnvironment™ is a high performance local environmental chamber providing excellent EMI- and light-tight shielded test environment for ultra-low noise, low capacitance measurements.

MPI ShieldEnvironment™ allows for testing with up to 4-port RF or up to 8-ports DC/Kelvin or a combination of those configurations. MPI ShieldCap™ provides easy reconfiguration of measurement setup as well as EMI/noise shielding - These all makes a great difference to conventional systems, especially in a day-to-day operation.

ShieldEnvironment™ Electrical Specifications*

EMI shielding	> 30 dB (typical) @ 1 kHz to 20 GHz
Light attenuation	≥ 130 dB
Spectral noise floor	≤ -180 dBVrms/rtHz (≤ 1 MHz)
System AC noise	≤ 5 mVp-p (≤ 1 GHz)

*Including 4 MicroPositioners.

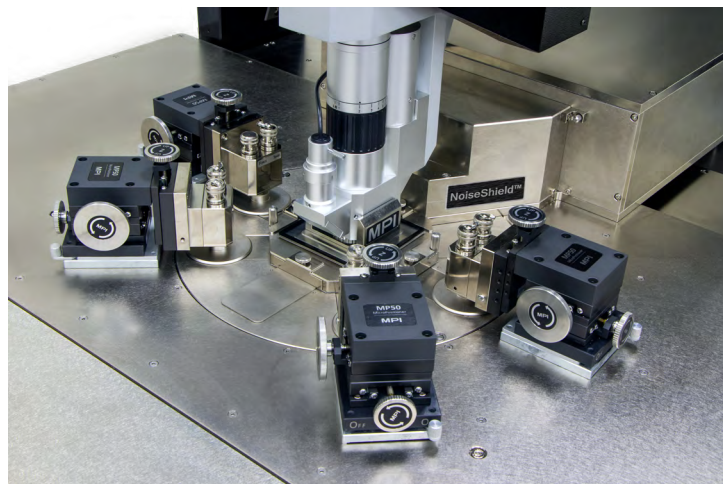


MPI NoiseShield™ Option for 1/f (Flicker) & RTN Measurements

MPI's exclusive NoiseShield™ offers in combination with MPI ShieldEnvironment™ for unsurpassed active EMI-Shielding of DUT and the measurement instrument (such as pre-amplifier unit). In addition, it provides all cables and connectors close to DUT.

The **NoiseShield™** option provides shortest possible cable lengths to reduce parasitic capacitance and to maximize test system roll-off frequency. It reduces external magnetic field influences on the measurement results and makes the 1/f, RTN Setup more robust and test lab location less independent.

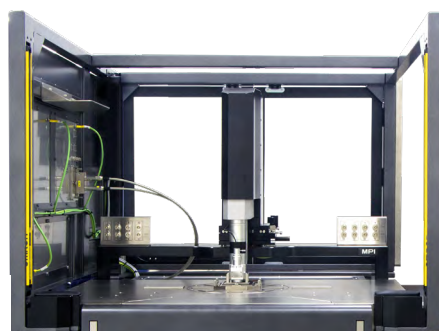
Low impedance cables (for DC or RF pad design), excellent low-impedance system's grounding and ferrite cores on the unique MPI Kelvin probes are part of the delivery in order to make the probe station completely "invisible" and the measurement results to reach the limit of the instrumentation.



SAFETY MANAGEMENT

Light Curtain

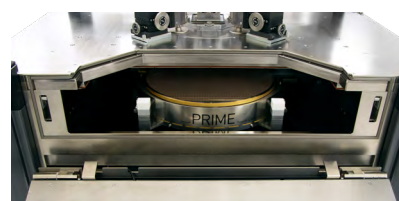
Light Curtain Interlock protects user from accidental high voltage shock by shutting down the instrument through interlock system. The interlock system at rear doors provides safety, easy and convenient initial measurement set-up.



WAFER LOADING

Loading or unloading of 150, 200 or 300 mm wafers or substrates is straight forward and intuitive. Special design of the chuck provides easy loading of a single IC or wafer fragments from the system front. SmartVacuum™ technology automatically recognizes size of the wafer on single IC. It also protects the wafer from unexpected release of vacuum due to inexperienced operation when the wafer is located in the IceFreeEnvironment™.

Easy access to the AUX chucks serves for quick exchange of RF calibration substrates, probe cleaning and planarization accessories.



Probe Hover Control™

MPI Probe Hover Control PHC™ allows easy manual control of probe contact and separation to wafer. Separation distance can accurately control with micrometer feedback for probe to wafer/pad positioning. Ease of use guarantees the safest operation by minimizing error during critical set-up and probe change operations.

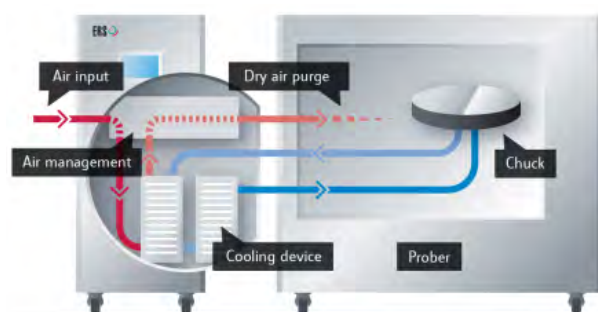


THERMAL CHILLER INTEGRATION

Minimized CDA Consumption

The CDA consumption is reduced by as much as 50% by purging IceFreeEnvironment™ with the re-used cold air of the chiller. Additional automated valve enables purge by Nitrogen*. Additionally, recycled CDA cools the system probe platen and the probe card.

**ERS patented technology.*



Picture is courteously provided by ERS.

INTEGRATED CONTROLS

Thermal chuck touchscreen control display is an alternative way of interaction with the thermal system. Its ergonomic location supports an operator when keying commands and monitoring system status. The fully integrated intelligent hardware control panel is design for intuitive and safe system control and operation. All these significantly increase the speed and improve convenience of the system interaction work flow.

The keyboard and mouse are placed on the sliding tray right below the system control panel. Both can control test instrumentation, if required.

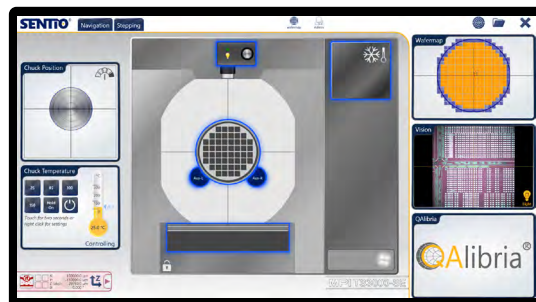
USB port is also in front of the system. It removes any hassles when exchanging data.



SOFTWARE SOLUTION

Unique and revolutionary multi-touch operation software SENTIO® controls MPI automated engineering probe systems. Its simple and intuitive operation concept significantly saves operator training time. Scroll, Zoon, and Move functions mimic modern smart mobile device interface. Switching between applications is just a matter of a simple finger swipe.

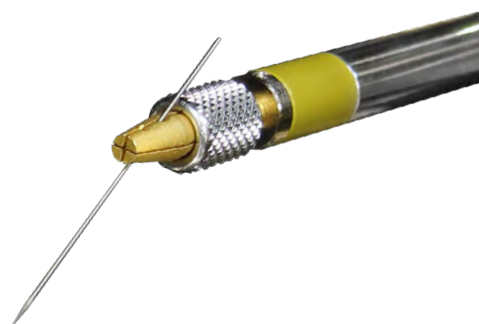
SENTIO® makes everyone the system operation expert in just minutes.



HIGH POWER PROBES

High Voltage Probes (HVP)

Low leakage probes specially designed to withstand high voltage up to 10 kV (coaxial) and 3 kV (triaxial). Choice of various connectors options such as Keysight Triax/UHV, Keithley Triax/UHV, SHV or Banana.



High Current Probe (HCP)

High performance probes specially designed for on wafer measurement of high current up to 200 A (pulse). MPI multi-fingers high current probes are single piece construction to efficiently handle high current and provide low contact resistance.



HIGH POWER PROBES - SELECTION GUIDE

	High current probes			High voltage probes		
	3 fingers	5 fingers	7 fingers	PA-HVT	PA-HVC	PA-HVC-10KV
Max current	40 A	65 A	100 A	2 A	2 A	2 A
Max voltage	500 V	500 V	500 V	3,000 V	5,000 V	10,000 V
Residual resistance (Typical)	≤ 5 mΩ	≤ 3 mΩ	≤ 1 mΩ	--	--	--
Leakage @ max. V	--	--	--	≤ 1 pA	≤ 600 pA	> 35 TΩ
Connector options	Banana ^[3] plug or BNC ^[4]			HV triaxial ^[2]	SHV	10 KV UHV or banana ^[3] plug
Replaceable tip	Yes	Yes	Yes	Yes	Yes	Yes
Probe pitch ^[1]	350 μm (Std)	350 μm (Std)	350 μm (Std)	Single needle	Single needle	Single needle

^[1]Configurable

^[2]Keysight or Keithley

^[3]Banana: 100 A max, 1 ms max PW, 1% max PLC

^[4]BNC: 40 A max, 1 ms max PW, 1% Max PLC

ULTRA HIGH POWER PROBES

Ultra High Power Probe (UHP)

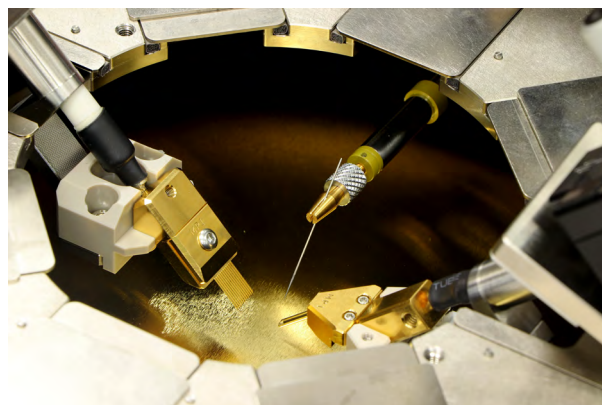
Designed for Ultra high voltage and current on wafer measurement up to 10 kV/600 A (pulse). MPI replaceable multi-fingers probes tips and probe arms are design for low contact resistance for ultra-high current measurement and to support ultra-high voltage of up to 10 KV, without having to change probes for high voltage and current application.



ULTRA HIGH POWER PROBES - SELECTION GUIDE

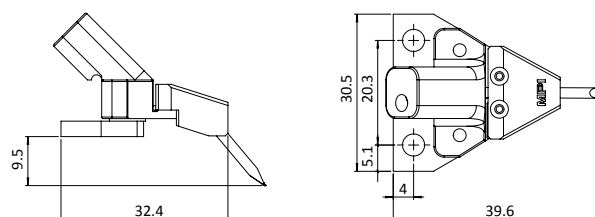
	1 finger	4 fingers	6 fingers	8 fingers	12 fingers
Max current*	20 A	80 A	120 A	160 A	250 A
Max voltage	10 KV	10 KV	10 KV	10 KV	10 KV
Residual resistance (Typical)	≤ 5 mΩ	≤ 3 mΩ	≤ 1 mΩ	≤ 1 mΩ	≤ 1 mΩ
Connector options	Banana	Banana	Banana	Banana	Banana
Replaceable tip	Yes	Yes	Yes	Yes	Yes
Probe tip width	250 μm	250 μm	250 μm	250 μm	250 μm
Probe pitch	--	650 μm	650 μm	650 μm	650 μm

*1 ms Max PW, 0.4% max PLC

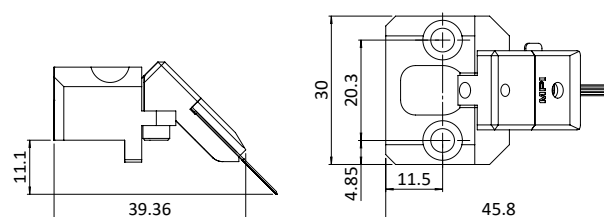


DIMENSIONS

High current probe



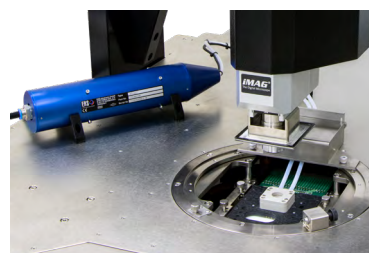
Ultra High Power probe



ANTI-ARCING SOLUTIONS

Optional Anti-Arcing Probe Card

In addition, MPI is offering optional temperature control of the pressurized air in a range of 20 to 200 °C, which correlate direct with the chuck set temperature. High-voltage testing without arcing at higher temperatures are possible now.



Optional Anti-Arcing LiquidTray™

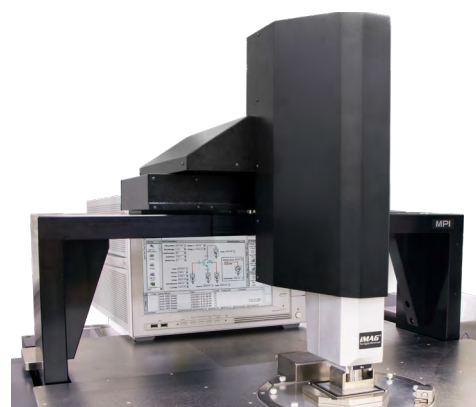
Specially designed anti-arcing LiquidTray™ can be used for arcing suppressing by simply place on the high power chuck surface. Wafers can be safely placed inside the tray to submerge in the liquid for arcing free high voltage test.

MICROSCOPE MOVEMENT

XYZ Programmable

XY - Travel range*	50 x 50 mm / 300 x 300 mm
Resolution	1 μm (0.04 mils)
Repeatability	≤ 2 μm (0.08 mils)
Accuracy	≤ 5 μm (0.2 mils)
Z - Travel range	140 mm
Resolution	0.05 μm (0.002 mils)
Repeatability	≤ 2 μm (0.08 mils)
Accuracy	≤ 4 μm (0.16 mils)

*In case of ShieldEnvironment™ X x Y: 25 mm x 25 mm



NON-THERMAL CHUCKS

Wafer Chuck	Standard	Triaxial
Connectivity	Coax BNC (f)	Kelvin Triax (f)
Diameter	310 mm with 2 integrated AUX areas	
Material	Nickel plated aluminum (flat with 0.5 mm holes)	
Chuck surface	Planar with 0.5 mm diameter holes in centric sections	
Vacuum holes sections (diameter)	4, 24, 48, 72, 96, 120, 144, 168, 192, 216, 240, 264, 288 mm	
SmartVacuum™ distribution	In front for single DUT 4x4 mm (4 holes) and 75 mm (3 in) In center for 150, 200, 300 mm (6, 8, 12 in)	
Surface planarity	$\leq \pm 5 \mu\text{m}^{**}$	
Rigidity	$< 15 \mu\text{m} / 10 \text{ N @edge}$	

*Single DUT testing requires higher vacuum conditions dependent upon testing application.

**By using SENTIO® topography

Triaxial RF Wafer Chuck

Connectivity	Kelvin Triax (f)
Diameter	310 mm with 2 integrated AUX chucks
Material	Nickel plated aluminum (flat with 0.5 mm holes)
Chuck surface	Planar with 0.5 mm diameter holes in centric sections
Vacuum holes sections (diameter)	4, 24, 48, 72, 96, 120, 144, 168, 192, 216, 240, 264, 288 mm
SmartVacuum™ distribution	In front for single DUT 4x4 mm (4 holes) and 75 mm (3 in) In center for 150, 200, 300 mm (6, 8, 12 in)
Surface planarity	$\leq \pm 5 \mu\text{m}^{**}$
Rigidity	$< 15 \mu\text{m} / 10 \text{ N @edge}$

*Single DUT testing requires higher vacuum conditions dependent upon testing application.

**By using SENTIO® topography

Auxiliary Chuck

Quantity	2 AUX chucks
Position	Integrated to front side of main chuck
Substrate size (W x L)	Max. 25 x 25 mm (1 x 1 in)
Material	Ceramic, RF absorbing material for accurate calibration
Surface planarity	$\leq \pm 5 \mu\text{m}$
Vacuum control	Controlled independently, separate from chucks

Electrical Specification (Coax)

Operation voltage	In accordance with EC 61010, certificates for higher voltages available upon request
Maximum voltage between chuck top and GND	500 V DC
Isolation	$> 2 \text{ G}\Omega$

Electrical Specification (Triax)

Chuck Isolation	At 10 V
Force-to-Guard	$> 5 \text{ T Ohm}$
Guard-to-Shield	$> 1 \text{ T Ohm}$
Force-to-Shield	$> 5 \text{ T Ohm}$

HIGH POWER THERMAL CHUCKS

Specifications	TC-300NP Series		TC-300NTP Series		TC-300HP Series		
Max. Voltage	1.1 kV		3 kV		3 kV Triax or 10 kV Coax		
Connectivity	Keithley Kelvin Triax (f)		MPI Kelvin Triax (f)		MPI Kelvin Triax (f)		
Temperature Range - Minimum	-60 °C, -40 °C, -10 °C, 20 °C or 35 °C versions						
Temperature Range - Maximum	200 °C		200 °C		300 °C		
Temperature control method	Cooling air / Resistance heater						
Coolant	Air (user supplied)		Air (user supplied)		Air (user supplied)		
Smallest temperature selection step	0.1 °C		0.1 °C		0.1 °C		
Chuck temperature display resolution	0.01 °C		0.01 °C		0.01 °C		
External touchscreen display operation	Yes		Yes		Yes		
Temperature stability	±0.5 °C		±0.5 °C		±0.5 °C		
Temperature accuracy	±0.1 °C		±0.1 °C		±0.1 °C		
Control method	Low noise DC/PID		Low noise DC/PID		Low noiseDC/PID		
Chuck pinhole surface plating	Gold** (others on requests)						
SmartVacuum™ distribution*	In front for single DUT 4x4 mm (4 holes) and 75 mm (3 in) In center for 150, 200, 300 mm (6, 8, 12 in)						
Temperature sensor	Pt100 1/3DIN, 4-line wired						
Temperature uniformity	< ±0.5 °C at ≤ 200 °C		< ±0.5 °C at ≤ 200 °C		< ±0.5 °C at ≤ 200 °C < ±1 °C at > 200 °C		
Surface flatness and base parallelism	< ±12 μm		< ±12 μm		< ±12 μm		
Heating rates**							
-60 to 25 °C	< 12 min		< 15 min		< 20 min		
-40 to 25 °C	< 10 min		< 12 min		< 18 min		
-10 to 25 °C	< 8 min		< 10 min		< 15 min		
35 to 200 °C	< 15 min		< 18 min		< 25 min		
20 to 200 °C	< 18 min		< 20 min		< 32 min		
35 to 300 °C	N/A		N/A		< 40 min		
20 to 300 °C	N/A		N/A		< 45 min		
Cooling rates** (faster w. -60°C chiller)							
25 to -10 °C	< 15 min / < 28 min		< 17 min / < 30 min		< 20 min		
25 to -40 °C	< 35 min / < 55 min		< 40 min / < 65 min		< 60 min		
20 to -60 °C	< 40 min		< 45 min		< 90 min		
200 to 35 °C	< 28 min		< 30 min		< 40 min		
200 to 25 °C	< 28 min		< 30 min		< 40 min		
300 to 35 °C	N/A		N/A		< 50 min		
300 to 25 °C	N/A		N/A		< 60 min		
Leakage							
@ Voltage and:	10 V	1.1 kV	10 V	3 kV	10 V	3 kV	10 kV
@ -60 °C	< 2 pA	< 220 pA	< 300 fA	< 100 pA	< 30 fA	< 10 pA	< 6 nA
@ 25 °C	< 1 pA	< 110 pA	< 150 fA	< 50 pA	< 15 fA	< 5 pA	< 6 nA
@ 200 °C	< 1 nA	< 110 nA	< 300 fA	< 150 pA	< 30 fA	< 10 pA	< 15 nA
@ 300 °C	N/A	N/A	N/A	N/A	< 50 fA	< 15 pA	< 40 nA

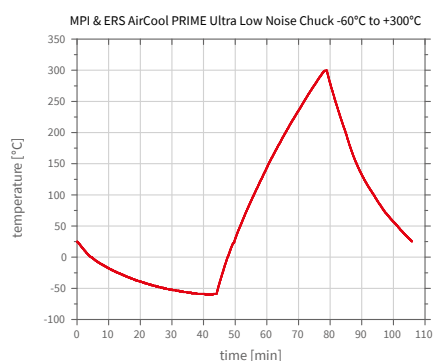
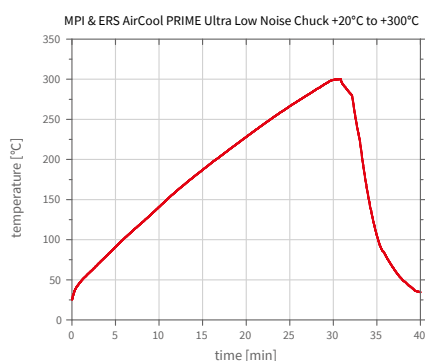
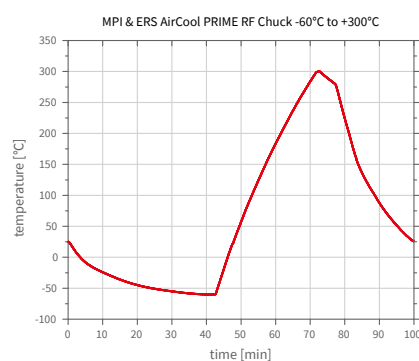
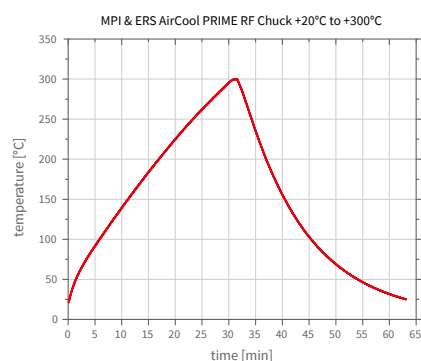
Capacitance

Force-to-Guard	< 1600 pF	< 600 pF	< 600 pF
Guard-to-Shield	< 2000 pF	< 2000 pF	< 2000 pF
Residual Capacitance	N/A	≤ 2.5 pF	≤ 2.5 pF

* Taiko-wafer support is optional available, please contact MPI local technical support.

** Typical values, depends on chiller type and facility supply, please check MPI FPS for the certain chuck and system.

TYPICAL TRANSITION TIME



ERS AirCool® Fusion*, Controller
Integrated Chiller -40 °C / -60 °C



ERS AirCool® Fusion*, Controller
Integrated Chiller -10 °C

*ERS electronic GmbH patented solution



ERS and MPI's joint product AirCool® PRIME Chuck won "Electronics Industry Awards 2018" in the category, "Test, Measurement and Inspection Product of the year".

SYSTEM CONTROLLER SPECIFICATIONS

CPU	Intel Core i9
RAM	16 GB
64 bit operating system	Windows 11 Enterprise LTSC (English) 64 bit
Storage	500 GB SSD
LAN	1 x internal, 1 x external TCP/IP port
USB Ports	3 x internal, 1 x external
GPIB interface	Optional

SUPPORTED SOFTWARE PLATFORMS

Drivers	WaferPro / IC-CAP & EasyEXPERT from Keysight, BSIMPro & NoisePro from ProPlus, ACS from Keithley
Emulation mode	Available for various prober control software*

* Please contact your local support for more details.

FACILITY REQUIREMENTS

General Probe System

Power	100-240 V AC nominal ; 50/60 Hz
Vacuum	-0.9 bar
Compressed air	6.0 bar

REGULATORY COMPLIANCE

3rd party, TÜV tested according to

- IEC 61010-1: 2010 + A1:2016; EN 61010-1: 2010; IEC/EN 61010-2-010: 2014; IEC/EN 61010-2-081: 2015; EN ISO 12100: 2010; UL 61010-1: 2012/R: 2016-04; UL 61010-2-010: 2015; CAN/CSA-C22.2 No. 61010-1: 2012/U2: 2016-04; CAN/CSA-C22.2 No. 61010-2-010:2015

and certified for CE and US/Canada (NRTL), SEMI S2 and S8.

Copies of certificates are available on request

WARRANTY

- Warranty*: 12 months
- Extended service contract: contact MPI Corporation for more information

*See MPI Corporation's Terms and Conditions of Sale for more details.

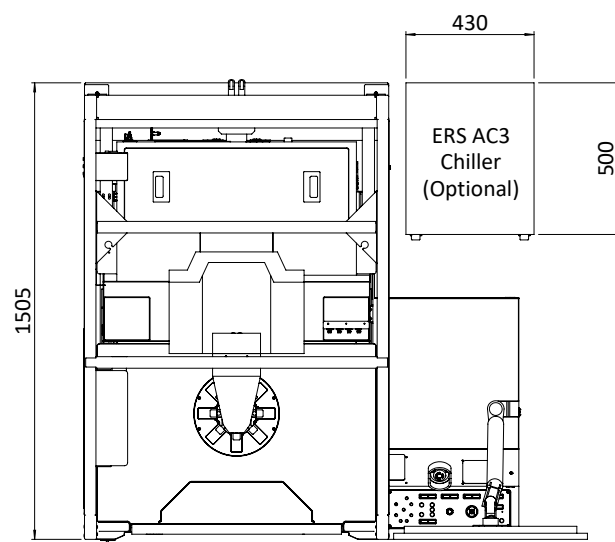
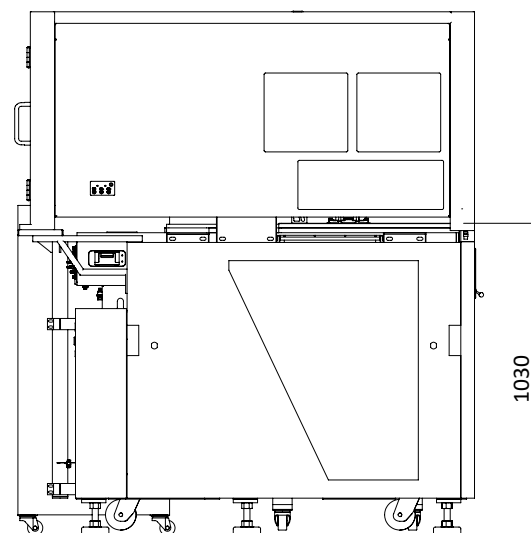
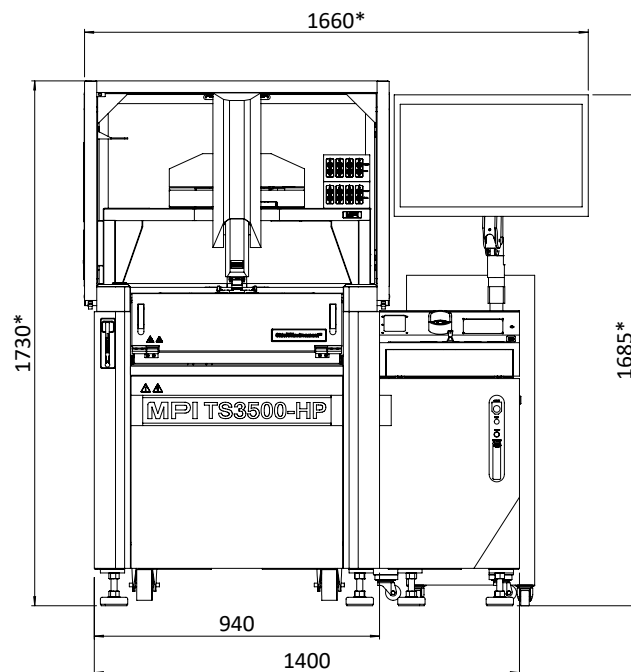
PHYSICAL DIMENSIONS

TS3500-HP

System dimensions (W x D x H) 1400 x 1505 x 1730 mm (55.1 x 59.3 x 68.1 in)

Weight 1150 kg

*Can increase depends on operator manual adjustment or interaction.

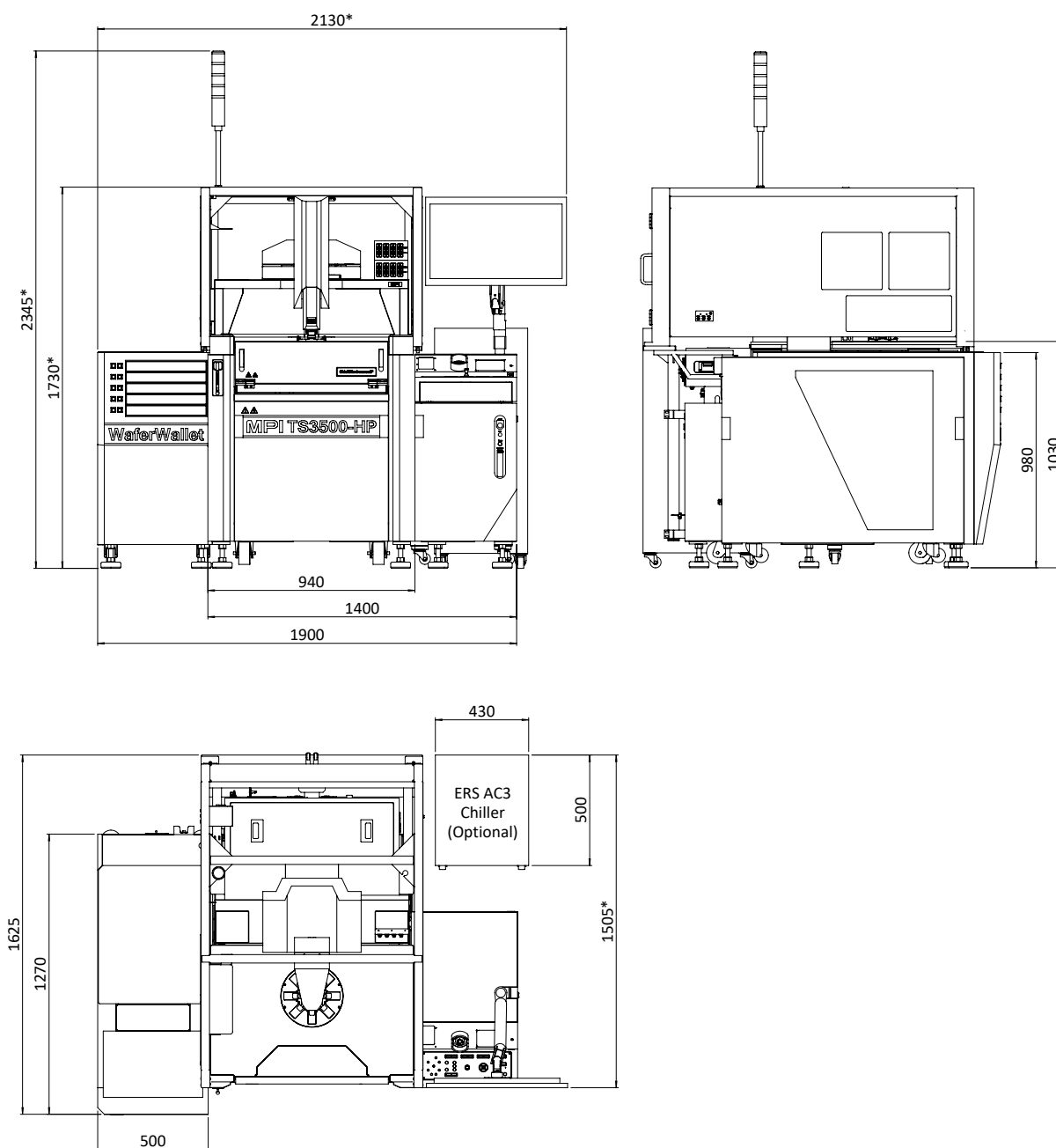


WaferWallet®

System dimensions (W x D x H)	500 x 1270 x 980 mm (19.7 x 50.0 x 38.6 in)
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Weight	200 kg
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*Can increase depends on operator manual adjustment or interaction.

TS3500-HP with WaferWallet®**MPI Global Presence**

Direct contact:

Asia region: ast-asia@mpi-corporation.com

EMEA region: ast-europe@mpi-corporation.com

America region: ast-americas@mpi-corporation.com

MPI global presence: for your local support, please find the right contact here:
mpi-corporation.com/ast/support/regional-sales-contact

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